# Wideband Quad 2:1 Video Switch

The NCS6433 is a wide bandwidth, bidirectional, Quad 2:1, NMOS-based video switch suitable for dealing with video signals such as RGB, composite, S-Video, and component video (YPbPr).

The NCS6433 is controlled by a single switch–enabled ( $\overline{OE}$ ) input. When  $\overline{OE}$  is low the switch is enabled and the A port is connected to the B port. When  $\overline{OE}$  is high the switch is disabled and the high–impedance state exists between the A and B ports. The line select (SEL) input controls the data path of the multiplexer/demultiplexer.

The NCS6433 has a wide bandwidth, low crosstalk, low on resistance, and fast switching times making it suitable for high-frequency video applications in high definition LCD TV's.

### Features

- Very Wide Frequency Bandwidth: 570 MHz
- Low Switch Serial Resistance R<sub>DS(on)</sub>, 4 Ω Typical
- Power Supply Voltage, 5 V
- Less Than 0.25 ns Bidirectional Maximum Propagation Delay Through Switch
- Low Quiescent Current: 3 µA Maximum
- Very Low Crosstalk, -80 dB Typical at 10 MHz
- Control Inputs are TTL/CMOS Compatible
- Ideal for High Definition Video Applications
- ESD HBM Protection 8 kV
- Fast Switching Better Than 10 ns
- Capable of Driving a High Current at the Output (>100 mA)
- Available in SOIC-16 or TSSOP-16 Package
- This is a Pb–Free Device

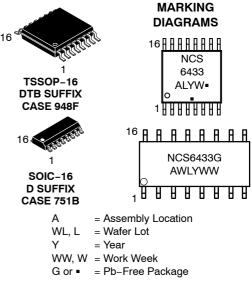
### **Typical Applications**

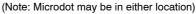
- Flat Panel Displays including LCDTV
- CRT Displays
- DVD Reader/Writer
- Set-Top Boxes

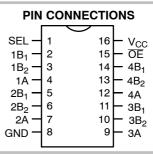


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#### **TRUTH TABLE**

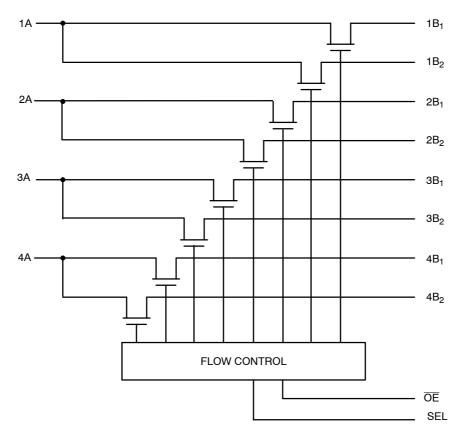
SEL	ŌE	Function
X	H	Open
L	L	A = B <sub>1</sub>
H	L	A = B <sub>2</sub>

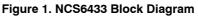
#### **PIN NAMES**

Pin	Description
ŌĒ	Bus Switch Enables
SEL	Select Inputs
А	Bus A
B <sub>1</sub> , B <sub>2</sub>	Bus B

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.





### **ORDERING INFORMATION**

Device Order Number	Package	Shipping <sup>†</sup>
NCS6433DR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
NCS6433DTBR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### ATTRIBUTES

Characteristics		Value
ESD Protection Human Body Model, R = 1000 $\Omega$ , C = 100 pF (Note 1) Machine Model	F I/O Pins 2–7, 9–14 All Pins All Pins	8 kV 2 kV 100 V
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in.
Meets or exceeds JEDEC Spec EIA/JESD78	3 IC Latch-up Test	

1. Meets or exceeds JEDEC spec JESD22-A114-B.

2. For additional information, see Application Note AND8003/D

### MAXIMUM RATINGS

Parameter			Value	Unit
DC Supply Voltage		V <sub>CC</sub>	-0.5 to +5.5	V
DC Input Voltage		VI	-0.5 to +5.5	V
DC Output Voltage		Vo	-0.5 to +5.5	V
DC Input Diode Current		Ι <sub>ΙΚ</sub>	- 50	mA
DC Output Diode Current		I <sub>OK</sub>	- 50	mA
DC Output Sink Current		Ι <sub>Ο</sub>	128	mA
DC Supply Current per Supply Pin		I <sub>CC</sub>	±100	mA
DC Ground Current per Ground Pin		I <sub>GND</sub>	±100	mA
Storage Temperature Range		T <sub>STG</sub>	-65 to +150	°C
Lead Temperature, 1 mm from Case for 10 Seconds		ΤL	260	°C
Junction Temperature Under Bias (Note 3)		TJ	+150	°C
Thermal Resistance	SOIC-16 TSSOP-16	$\theta_{JA}$	125 170	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

3. Maximum electrical ratings are defined as those values beyond which damage to the device may occur at  $T_A = +25^{\circ}C$ .

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	Operating, Data Retention Only	4.75	5.25	V
VI	Input Voltage	(Note 4)	0	5.25	V
Vo	Output Voltage	(HIGH or LOW State)	0	5.25	V
T <sub>A</sub>	Operating Free-Air Temperature		-40	+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate Switch I/O	Switch Control Input V <sub>CC</sub> = 5.0 V $\pm$ 0.5 V	0	DC 5	ns/V

4. Unused control inputs may not be left open. All control inputs must be tied to a high or low logic input voltage level.

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min	Тур*	Max	Unit
V <sub>IK</sub>	Clamp Diode Voltage	I <sub>IN</sub> = -18 mA	4.5	-1.2	-0.8		V
V <sub>IH</sub>	High-Level Input Voltage		4.0 to 5.5	2.0			V
V <sub>IL</sub>	Low-Level Input Voltage		4.0 to 5.5			0.8	V
ILI	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	5.5			±1.0	μA
I <sub>OZ</sub>	Off-State Leakage Current	$0 \le A, B \le V_{CC}$	5.5			±1.0	μΑ
R <sub>ON</sub>	Switch On Resistance (Note 5)	$V_{\text{IN}}$ = 1 V, $I_{\text{ON}}$ = 13 mA, $R_{\text{L}}$ = 75 $\Omega$	4.5		4.0	7.0	Ω
		$V_{\text{IN}}$ = 2 V, $I_{\text{ON}}$ = 26 mA, $R_{\text{L}}$ = 75 $\Omega$	4.5		7.0	10	
I <sub>CC</sub>	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0$	5.5			3.0	μA
$\Delta I_{CC}$	Increase In I <sub>CC</sub> per Input	One input at 3.4 V, Other inputs at $V_{CC}$ or GND	5.5			2.5	mA

\*Typical values are at V<sub>CC</sub> = 5.0 V and T<sub>A</sub> = 25°C.
5. Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the two (A or B) pins.

### AC ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = -40°C to +85°C, C<sub>L</sub> = 20 pF, RU = RD = 75 $\Omega$ unless otherwise specified) (Note 6)

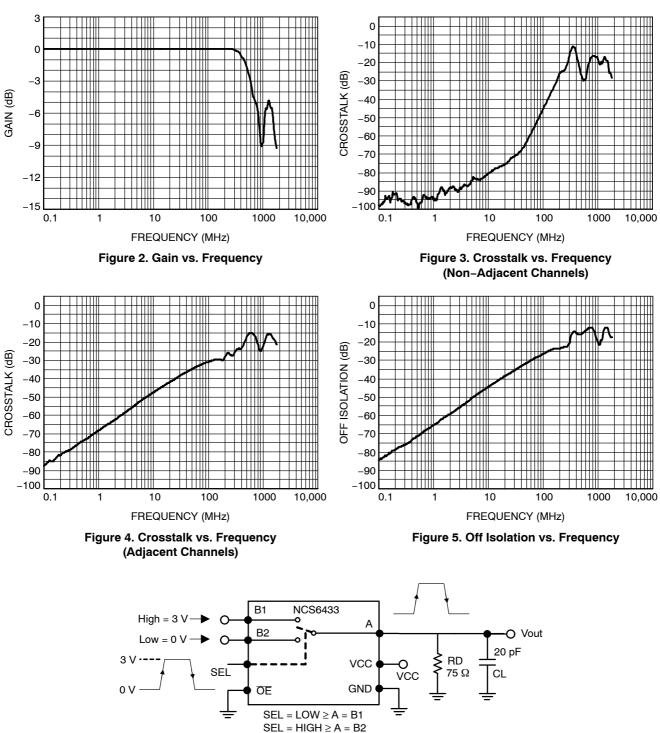
				V <sub>CC</sub> = 4.5–5.5 V		
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t <sub>ON</sub>	Turn On Time	$R_L$ = 75 Ω, $C_L$ = 20 pF, see Figure 7		2.8	5.0	ns
tOFF	Turn Off Time	$R_L$ = 75 Ω, $C_L$ = 20 pF, see Figure 7		1.4	5.0	ns
BW	-3 dB Bandwidth	$R_L = 150 \Omega$ , $T_A = 25^{\circ}C$			570	MHz
X <sub>talk</sub>	Crosstalk Adjacent Non-Adjacent	10 MHz, $C_L$ = 0 pF, $R_L$ = 150 $\Omega$		-47 -80		dB
Off <sub>ISO</sub>	Off Isolation	10 MHz, $C_L$ = 0 pF, $R_L$ = 150 $\Omega$		-48		dB

6. T\_A =  $+25^{\circ}$ C, parameters characterized but not tested.

### CAPACITANCES (Note 7)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
C <sub>IN</sub>	Control Pin Input Capacitance	V <sub>CC</sub> = 5.0 V		2.0		pF
C <sub>I/OA</sub>	A Port Input/Output Capacitance	$V_{CC} = \overline{OE} = 5.0 V$		5.0		pF
C <sub>I/OB</sub>	B Port Input/Output Capacitance	$V_{CC} = \overline{OE} = 5.0 V$		5.0		pF

7.  $T_A$  =  $+\,25^\circ C,\,f$  = 1 MHz, Capacitance is characterized but not tested.



### **TYPICAL CHARACTERISTICS**



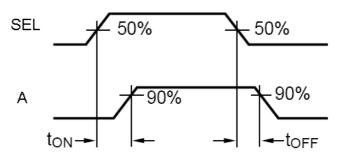


Figure 7. Turn-on and Turn-off Times

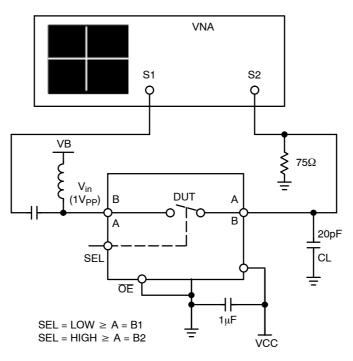
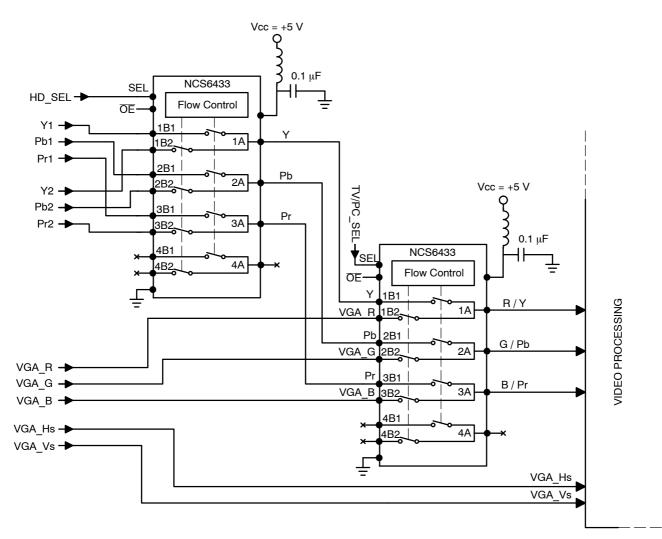


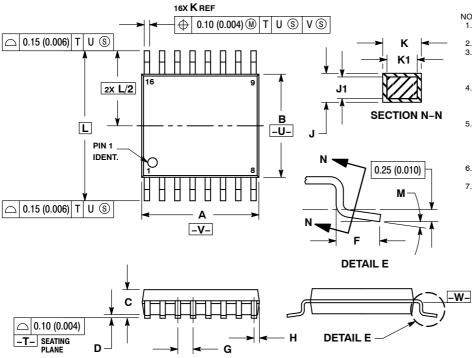
Figure 8. Gain, Crosstalk, Off-Isolation





### PACKAGE DIMENSIONS

TSSOP-16 CASE 948F-01 **ISSUE B** 

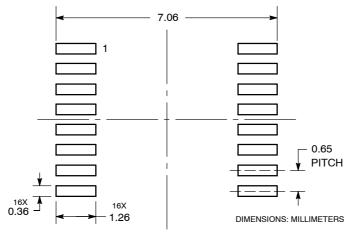


NOTES: 1. DIMENSIONING AND TOLERANCING PER

- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER. 2. З.
- 4.
- CONTROLLING DIMENSION: MILLIMETER.
   DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
   DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT 5.
- IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 6.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-. 7.

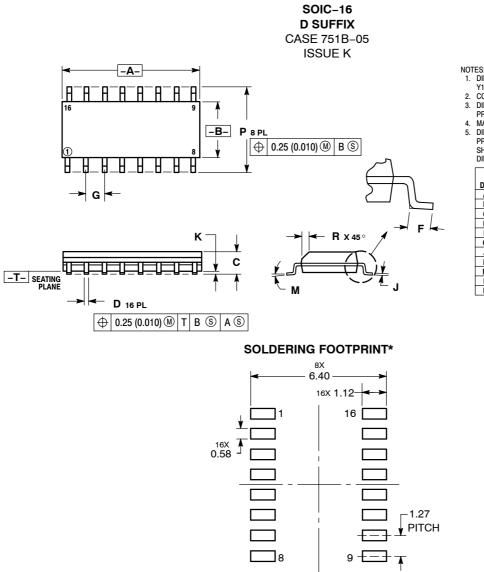
	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
н	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
ĸ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252	
Μ	0 °	8 °	0 °	8 °

SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS



DIMENSIONS: MILLIMETERS

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- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION

MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	1.27 BSC		BSC
J	0.19	0.25	0.008	0.009
Κ	0.10	0.25	0.004	0.009
М	0 °	7°	0°	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019